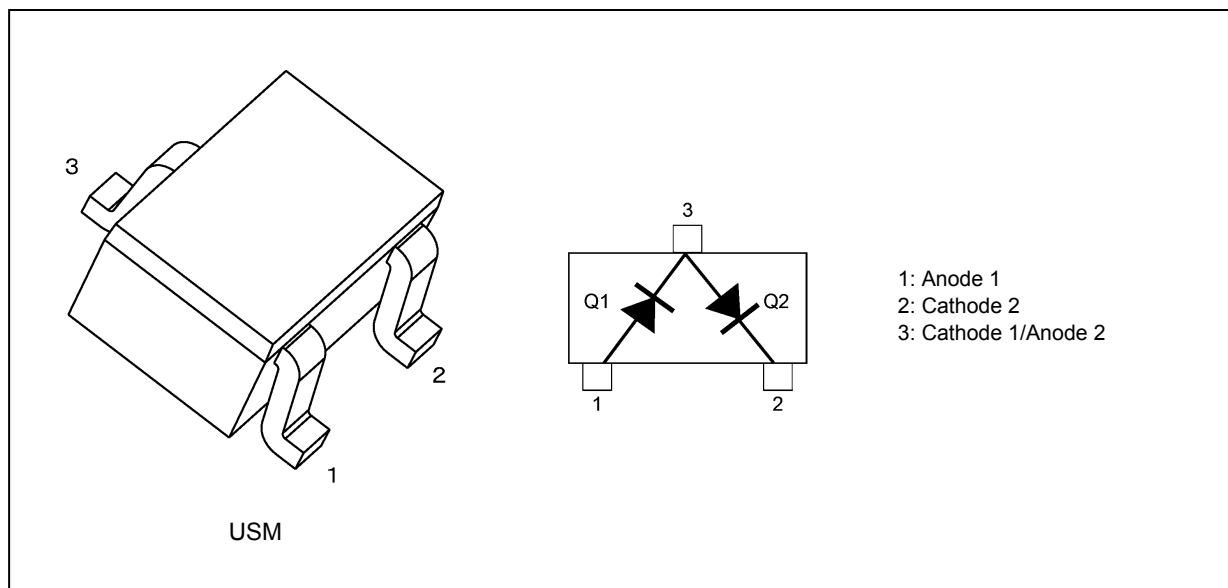


# BAV99W

## 1. Applications

- High-Speed Switching

## 2. Packaging and Internal Circuit



## 3. Absolute Maximum Ratings (Note) (Unless otherwise specified, $T_a = 25\text{ }^\circ\text{C}$ )

Characteristics	Symbol	Note	Rating	Unit
Peak reverse voltage	$V_{RM}$		100	V
Reverse voltage	$V_R$		100	
Peak forward current	$I_{FM}$	(Note 1)	500	mA
Average rectified current	$I_O$	(Note 2)	150	
Non-repetitive peak forward surge current	$I_{FSM}$	(Note 2), (Note 3)	2	A
Power dissipation	$P_D$		100	mW
Junction temperature	$T_j$		150	$^\circ\text{C}$
Storage temperature	$T_{stg}$		-55 to 150	

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Note 1: Unit rating. Total rating = Unit rating  $\times$  40%

Note 2: Unit rating. Total rating = Unit rating  $\times$  70%

Note 3: Measured with a 10 ms pulse.

Start of commercial production

2016-08

## 4. Electrical Characteristics (Unless otherwise specified, $T_a = 25\text{ }^\circ\text{C}$ )

Characteristics	Symbol	Test Condition	Min	Typ.	Max	Unit
Forward voltage	$V_F$ (1)	$I_F = 1\text{ mA}$	—	—	0.715	V
	$V_F$ (2)	$I_F = 10\text{ mA}$	—	—	0.855	
	$V_F$ (3)	$I_F = 50\text{ mA}$	—	—	1.00	
	$V_F$ (4)	$I_F = 150\text{ mA}$	—	—	1.25	
Reverse current	$I_R$ (1)	$V_R = 25\text{ V}$	—	—	30	nA
	$I_R$ (2)	$V_R = 80\text{ V}$	—	—	200	
Total capacitance	$C_t$	$V_R = 0\text{ V}, f = 1\text{ MHz}$	—	0.9	—	pF
Reverse recovery time	$t_{rr}$	$I_F = 10\text{ mA}$ , See Fig. 4.1.	—	—	4.0	ns

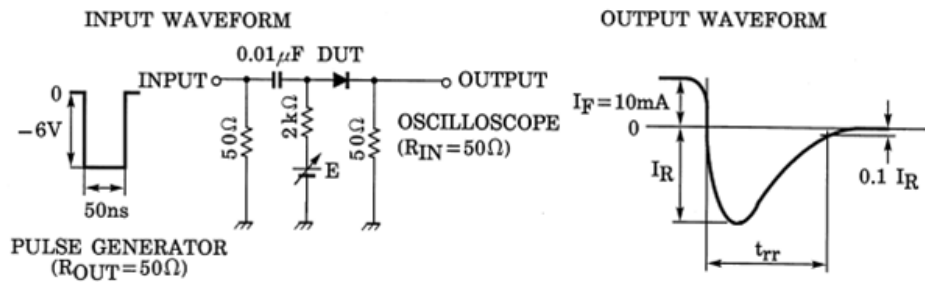
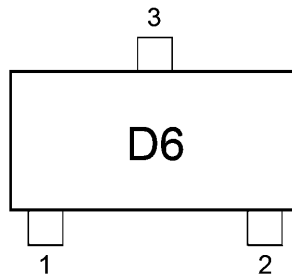
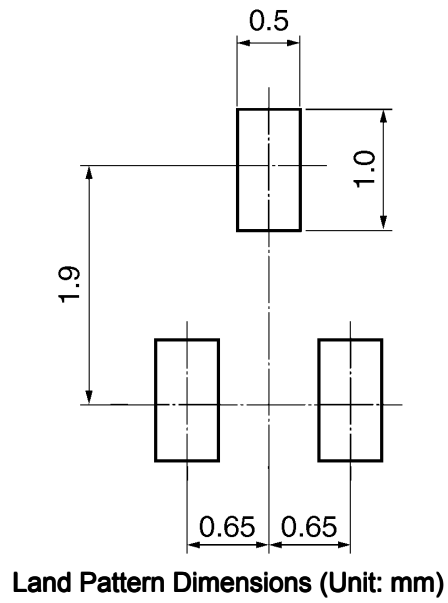


Fig. 4.1 Reverse recovery time ( $t_{rr}$ ) Test circuit

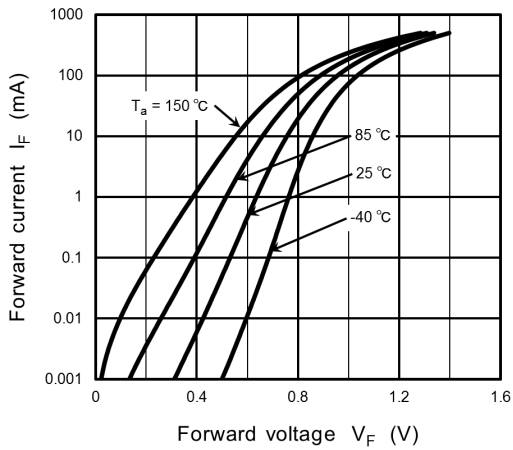
## 5. Marking



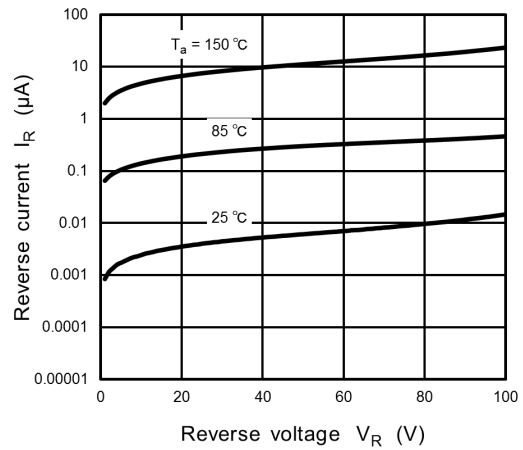
## 6. Land Pattern Dimensions (for reference only)



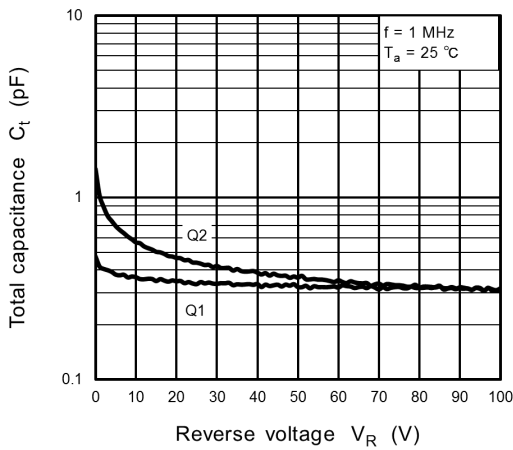
## 7. Characteristics Curves (Note)



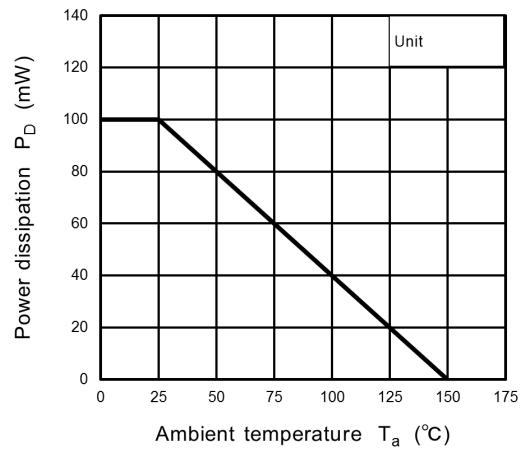
**Fig. 7.1  $I_F - V_F$**



**Fig. 7.2  $I_R - V_R$**



**Fig. 7.3  $C_t - V_R$**

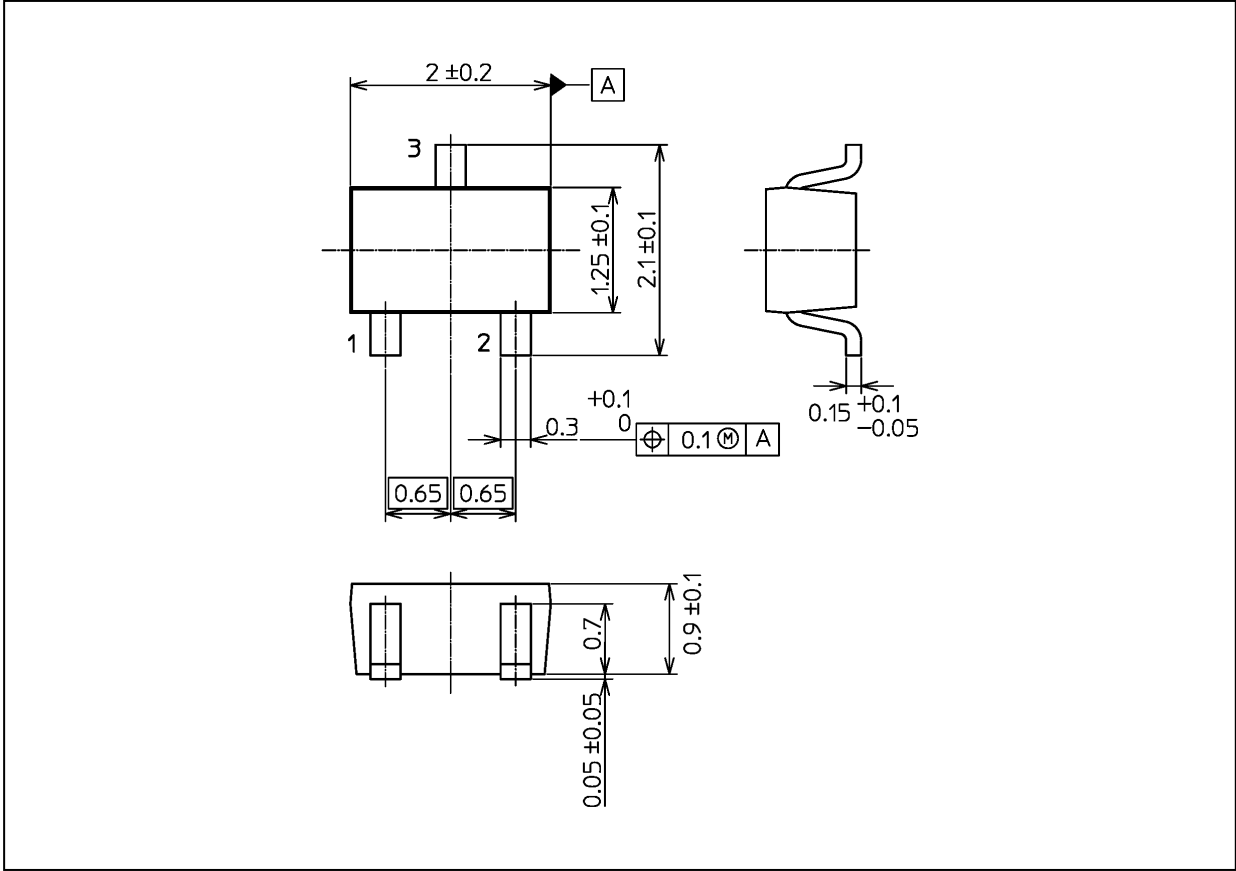


**Fig. 7.4  $P_D - T_a$**

Note: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.

Package Dimensions

Unit: mm



Weight: 6.0 mg (typ.)

Package Name(s)
JEDEC: SOT-323
Nickname: USM

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